L Number	Hits	Search Text	DB	Time stamp
2	67	((429/30-39.ccls. or h01m008$.ipc.) and modulus) and (@ad<19981120 @rlad<19981120)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:29
3	12	"196683"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 12:53
1	152	(429/30-39.ccls. or h01m008$.ipc.) and modulus	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 15:03
6	65	(429/30-39.ccls. or h01m008$.ipc.) and (shore or durometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:30
7	29	((429/30-39.ccls. or h01m008$.ipc.) and (shore or durometer)) and (@ad<19981120 @rlad<19981120)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 13:26
8	69	(429/30-39.ccls. or h01m008$.ipc.) and epoxy with silicon$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:30
9	21	((429/30-39.ccls. or h01m008$.ipc.) and epoxy with silicon$4) and (@ad<19981120 @rlad<19981120)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 13:26
10	13	29/623.4 and modulus	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:29
11	5	(29/623.4 and modulus) and (@ad<19981120 @rlad<19981120)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 15:04
12	4	29/623.4 and (shore or durometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:30
13	6	29/623.4.ccls. and epoxy with silicon$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 14:31
14	165	(429/30-39.ccls. or h01m008$.ipc. or 29/623.4.ccls.) and hardness	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 15:04
15	80	((429/30-39.ccls. or h01m008$.ipc. or 29/623.4.ccls.) and hardness) and (@ad<19981120 @rlad<19981120)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/22 15:04

C:\APPS\east\workspaces\196683.wsp